

**ABSTRACT OF THE DISCLOSURE**

The preferred embodiments provide a lead frame wherein a first air vent 29 and a second air vent 30 are formed in an air vent forming region 32. When resin-molding, one end of this first air vent 29 is disposed within the cavity, whereby air in the cavity when resin-molding can be completely released to the outside of the cavity. As a result, a package after resin-molding includes no unfilled regions or voids, whereby a semiconductor device with excellent product quality can be provided. In the background, air in cavities could not be completely released when resin-molding since, for instance, one air vent was provided at a position apart from the cavity region, and unfilled regions or voids were created.